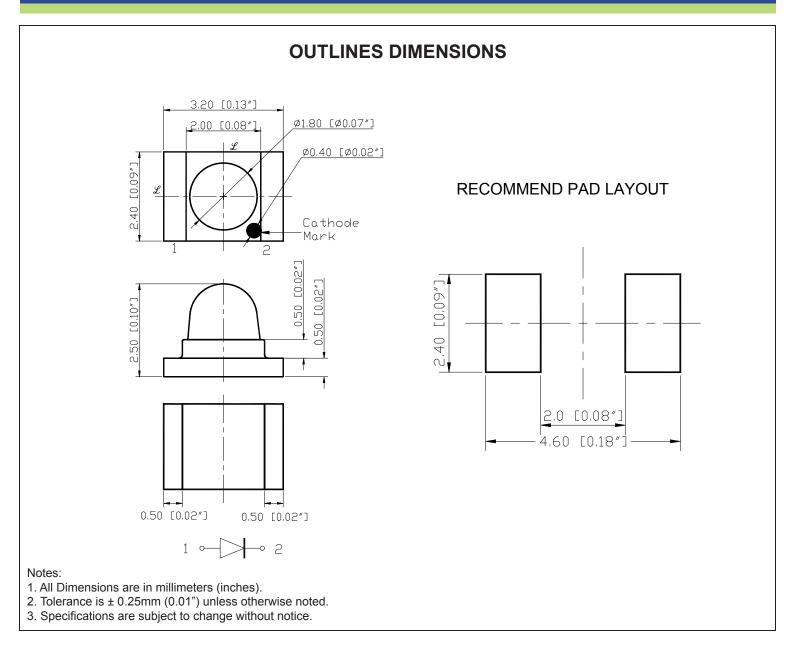


SPECIFICATIONS



Part Number	Chip Material	Color of Emission	Lens Type	Viewing Angle
CSD131B2C	InGaN	Blue	Water Clear	15°



ChromeLED Corp. reserves the right to make changes at any time in order to supply the best product possible. The most current version of this document will always be available at: www.chromeled.com

CSD131B2C



ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Max Rating	Unit
Power Dissipation	PD	111	mW
Pulse Current Forward Current	IFP	125	mA
Continuous Forward Current	IF	30	mA
Reverse Voltage	VR	5	V
Operating Temperature Range	Topr	-40~+80	°C
Storage Temperature Range	Тѕтс	-40~+85	°C
			- / -

IFP = Pulse Width \leq 10 ms, Duty Ratio \leq 1/10. Soldering Condition: 260 °C/ 5sec

OPTICAL-ELECTRICAL CHARACTERISTICS

(TA=25°C)

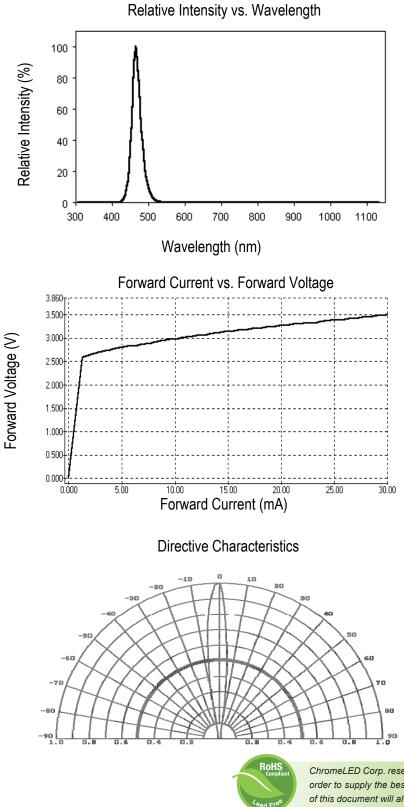
Parameter	Symbol	Test Condition	Value			Linit
			Min	Тур	Max	Unit
Luminous Intensity	lv	l⊧ = 20mA	1000	1700	-	mcd
Forward Voltage	VF	l⊧ = 20mA	-	3.1	3.7	V
Viewing Angle	201/2	l⊧ = 20mA	-	15	-	deg
Peak Wavelength	λP	l⊧ = 20mA	-	465	-	nm
Dominant Wavelength	λd	l⊧ = 20mA		470		nm
Spectral Line half-width	Δλ	l⊧ = 20mA	-	15	-	nm

*Tolerance of viewing angle: -10 / +5 deg.





OPTICAL CHARACTERISTIC CURVES

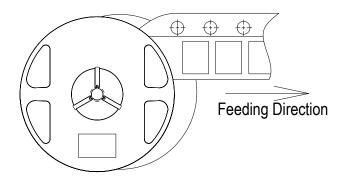


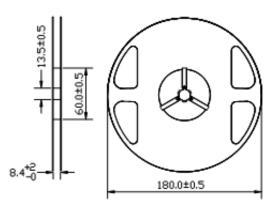


PACKAGING SPECIFICATION

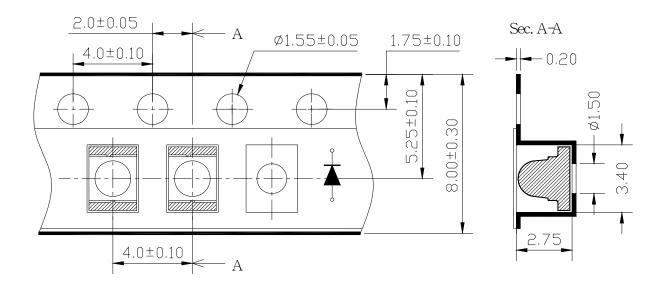
• Feeding Direction







• Dimensions of Tape (Unit: mm)







SOLDERING CONDITIONS – LAMP TYPE LED

- * Solder the LED no closer than 3mm from the base of the epoxy bulb. Soldering beyond the base of the tie bar is recommended.
- * Recommended soldering conditions

Dip Soldering			
Pre-Heat	100 °C Max		
Pre-Heat Time 60 Second Max			
Solder Bath Temperature	260 °C Max		
Dippng Time	5 Second Max		
Dipping Position	No lower than 3mm from the base of the epoxy		

Hand Soldering				
Temperature Soldering Time Position	3mm Series	Others		
	300 °C Max	350 °C Max		
	3 Second Max	3 Second Max		
	No closer than 3mm from the	No closer than 3mm from the		
	base of the epoxy	base of the epoxy		

- * Do not apply any stress to the lead. Particularly when heated.
- * The LED must not be repositioned after soldering.
- * After soldering the LEDs, the epoxy bulb should be protected from mechanical shock or vibration until the LEDs return to room temperature.
- * Direct soldering onto a PC board should be avoided. Mechanical stress to the resin may be caused by the PC board warping or from the clinching and cutting of the leadframes. When it is absolutely necessary, the LEDs may be mounted in this fashion, but, the user will assume responsibility for any problems. Direct soldering should only be done after testing has confirmed that no damage, such as wire bond failure or resin deterioration, will occur. LEDs should not be soldered directly to double sided PC boards because the heat will deteriorate the epoxy resin.
- * When it is necessary to clamp the LEDs to prevent soldering failure, it is important to minimize the mechanical stress on the LEDs.
- * Cut the LED leadframes at room temperature. Cutting the leadframes at high temperature may cause LED failure.

